

Title (en)

Flooring panel and method of laying such a panel

Title (de)

Fussbodenpaneel und Verfahren zum Verlegen eines solchen Paneels

Title (fr)

Panneau de plancher et procédé de pose d'un tel panneau

Publication

EP 1367194 B1 20080102 (DE)

Application

EP 03011897 A 20030527

Priority

- DE 10224540 A 20020531
- DE 10230819 A 20020708
- DE 10252864 A 20021112
- DE 10253236 A 20021115

Abstract (en)

[origin: DE20321446U1] The floor panel (2), of high density (HDF) or medium density (MDF) fiberboard or oriented strand board (OSB), can have a patterning layer on its upper surface (15), and a lower surface (7) against the ground. The edges are structured so that at least two panels can be locked together in the lateral (Q) and vertical (V) directions. The edges are shaped with positive fit structures (23,24) at one side edge with spaced vertical walls (21,22), displaced laterally and vertically to lock neighboring panels in the vertical direction. At the other side, a step (20) is cut out from the under side, with an inner (21) and an outer (22) wall to shape the positive fit structures. At the opposite edge, a projecting step (200) is cut out with an inner (210) and an outer (220) wall, in a matching shape to the positive fit structures.

IPC 8 full level

E04F 15/02 (2006.01)

CPC (source: EP)

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Citation (examination)

- WO 2004001157 A1 20031231 - WEITZER PARKETT GMBH & CO KG [AT], et al
- DE 10021897 A1 20011108 - KUNNEMEYER HORNITEX [DE]
- WO 02103135 A1 20021227 - KRONOSPAN TECH CO LTD [CY], et al

Cited by

DE102008046749A1; CN103572771A; CN103477003A; FR2885628A1; DE102008046749B4; HRP20060191B1; NO338807B1; US2022213694A1; US9032686B2; NL1024046C2; EP1420125A3; DE102012000468B4; EP3321448A3; WO2012139601A1; WO2007003805A3; WO2005118978A1; US10947741B2; US11441319B2; US9206611B2; US11891815B2; DE102012000468A1; US11591805B2; EP1702119B1; WO2019197666A1; US9611656B2; US9677285B2; US10156078B2; US10233653B2; US10626619B2; US10738480B2; US10738481B2; US10738482B2; EP3321448B1

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